

Title: MULTI-STEP DRY ETCHING METHOD
FOR SOI WAFER

Inventor(s): Michihiko YANAGISAWA et al.

Application No.: New Application

Docket No.: 506212001200

FIG. 1

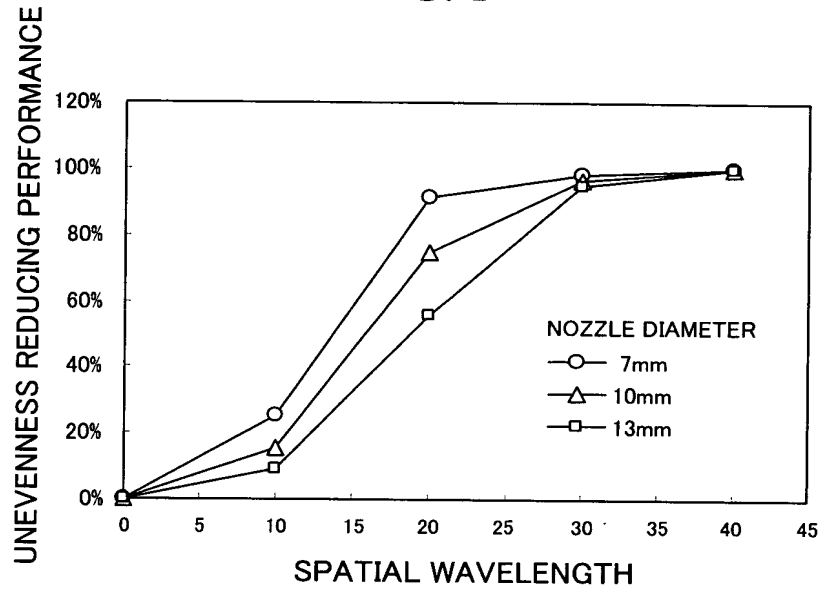
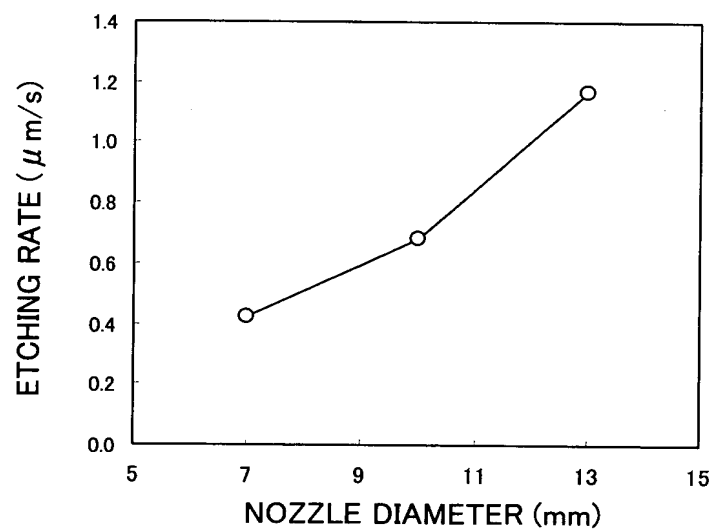


FIG. 2



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FIG. 3

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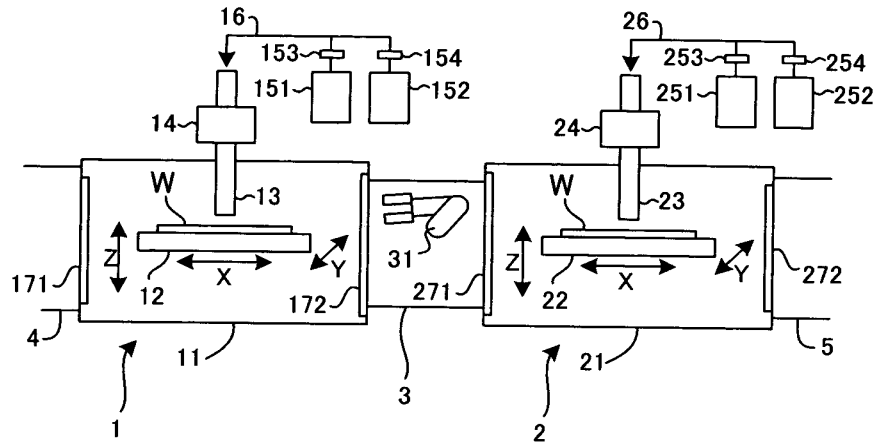
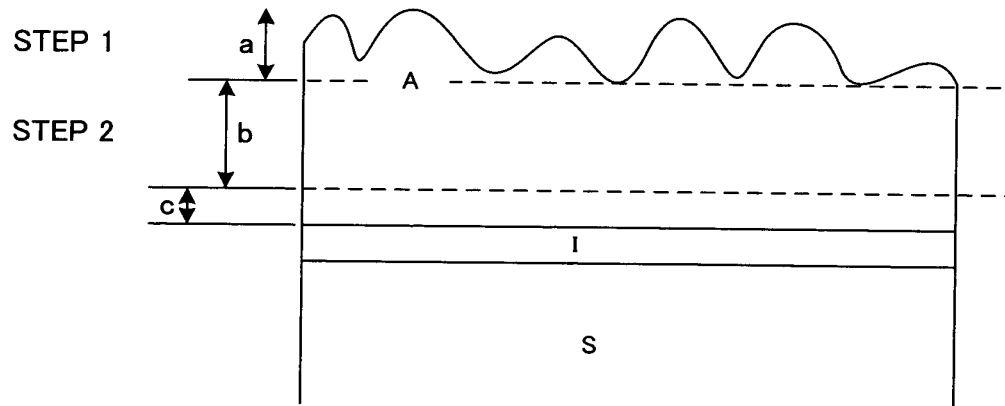


FIG. 4



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FIG. 5

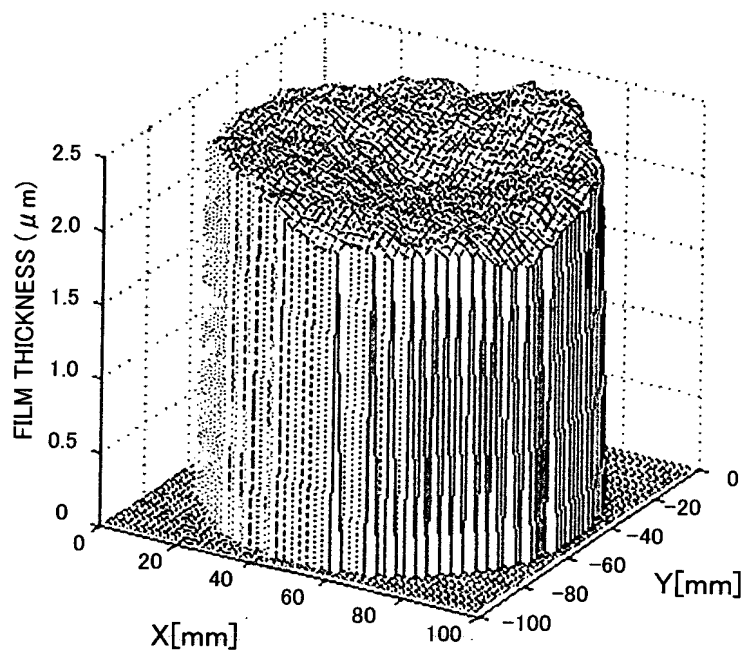
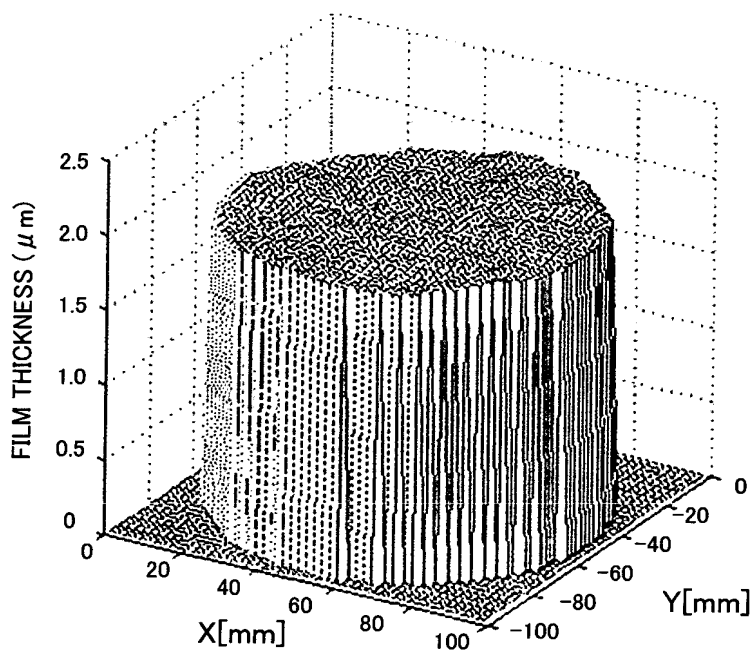


FIG. 6



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FIG. 7

